

## Product Change Notification - JAON-30IVHP500

**Date:** 06 Jul 2017

**Product Category:** Capacitive Touch Sensors; 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

**Notification subject:** CCB 3001 Initial Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

**Notification text:** **PCN Status:**  
Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

**Pre Change:**

Assembled at MTAI using palladium coated copper (PdCu) bond wire.

**Post Change:**

Assembled at MTAI using palladium coated copper (PdCu) bond wire or assembled at MMT using palladium coated copper with gold flash (CuPdAu) bond wire.

**Pre and Post Change Summary:**

	Pre Change	Post Change	
<b>Assembly Site</b>	MTAI Assembly Site	MTAI Assembly Site	MMT Assembly Site
<b>Wire material</b>	PdCu Wire	PdCu Wire	CuPdAu Wire
<b>Die attach material</b>	3280	3280	3280
<b>Molding compound material</b>	G600	G600	G600
<b>Lead frame material</b>	CDA194	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	July 2017				-->	October 2017			
Workweek	27	28	29	30		40	41	42	43
Initial PCN Issue Date	X								
Qual Report Availability								X	
Final PCN Issue Date								X	

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

**Revision History:**

**July 6, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

- [PCN\\_JAON-30IVHP500\\_Qual Plan.pdf](#)
- [PCN\\_JAON-30IVHP500\\_Affected CPN.pdf](#)
- [PCN\\_JAON-30IVHP500\\_Affected CPN.xlsx](#)

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**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN #: JAON-30IVHP500**

**Date:  
June 15, 2017**

**Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.**

**Purpose:** Qualification of MMT as an additional assembly site using palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

**CCB No.:** 3001

<b><u>Misc.</u></b>	<b>Assembly site</b>	MMT
	<b>BD Number</b>	BDM-001364 rev A
	<b>MP Code (MPC)</b>	LEBC14N2XAXF
	<b>Part Number (CPN)</b>	PIC18F25K80-E/SS
<b><u>Lead-Frame</u></b>	<b>Paddle size</b>	153x200 mils
	<b>Material</b>	CDA194
	<b>Surface</b>	Bare Cu
	<b>Treatment</b>	BOT
	<b>Process</b>	Stamped
	<b>Lead-lock</b>	No
	<b>Part Number</b>	10102834
	<b>Lead Plating</b>	Matte Tin
	<b>LF Matrix (RowxColumn)</b>	12x4
<b>Strip test capable</b>	Yes	
<b><u>Bond Wire</u></b>	<b>Material</b>	CuPdAu
<b><u>Die Attach</u></b>	<b>Part Number</b>	3280
	<b>Conductive</b>	Yes
<b><u>MC</u></b>	<b>Part Number</b>	G600
<b><u>PKG</u></b>	<b>PKG Type</b>	SSOP
	<b>Pin/Ball Count</b>	28
	<b>PKG width/size</b>	0.209"
<b><u>Die</u></b>	<b>Die Thickness</b>	15
	<b>Die Size</b>	135.5x138.3 mils
<b>MSL Classification</b>		L1/260C

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	24	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		Required for any reduction in wire bond thickness.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp.85°C. 1 lot to be tested at 125C	45	5	1	50	0	25	For hot temp testing, pre/post test 1 lot at 85°C and 125°C (if applicable)
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. Extend HAST to 192 hrs post stress test at 25C. 1 lot to be tested at 125C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C. Extend HAST to 192 hrs post stress test at 25C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. 1 lot to be tested at 125C	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

JAON-30IVHP500 - CCB 3001 Initial Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Affected Catalog Part Numbers (CPN)

<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
C0001RIC00-I/SS
C0001RIC00T-I/SS
C0003RIC03T-I/SS028
HA0130-I/SS
HA0130T-I/SS
HA1018-I/SS
HA1018T-I/SS
HA1127-I/SS
HA1127T-I/SS
HA1138-I/SS
HA1138T-I/SS
HA1598-E/SS
HA1598T-E/SS
HA1630-I/SO
HA1630T-I/SO
HA1631-I/SO
HA1631T-I/SO
HA1839-I/SS
HA1839T-I/SS
HA1930C-I/SS
HA2003-I/SS
MCV282B-I/SS
MCV283B-I/SS
MCV283BT-I/SS
MTCH6102-I/SS
MTCH6102T-I/SS
MTR5010-I/SS
MTR5010T-I/SS
MTR9833-I/SS
MTR9833T-I/SS
PIC16F1512-E/SS
PIC16F1512-I/SS
PIC16F1512-I/SSC03
PIC16F1512-I/SSC04
PIC16F1512T-I/SS
PIC16F1512T-I/SSC03
PIC16F1512T-I/SSC04
PIC16F1513-E/SS
PIC16F1513-I/SS
PIC16F1513T-E/SS
PIC16F1513T-I/SS
PIC16F1516-E/SS
PIC16F1516-I/SS

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC16F1516-I/SS024
PIC16F1516-I/SSC01
PIC16F1516-I/SSC02
PIC16F1516T-E/SS
PIC16F1516T-I/SS
PIC16F1516T-I/SS021
PIC16F1516T-I/SS022
PIC16F1516T-I/SS024
PIC16F1516T-I/SS025
PIC16F1516T-I/SSC01
PIC16F1516T-I/SSC02
PIC16F1518-E/SS
PIC16F1518-I/SS
PIC16F1518T-I/SS
PIC16F1713-E/SS
PIC16F1713-I/SS
PIC16F1713T-I/SS
PIC16F1716-E/SS
PIC16F1716-I/SS
PIC16F1716T-I/SS
PIC16F1718-E/SS
PIC16F1718-I/SS
PIC16F1718T-I/SS
PIC16F1773-E/SS
PIC16F1773-I/SS
PIC16F1773T-I/SS
PIC16F1776-E/SS
PIC16F1776-I/SS
PIC16F1776T-I/SS
PIC16F1778-E/SS
PIC16F1778-I/SS
PIC16F1778T-I/SS
PIC16F1782-E/SS
PIC16F1782-I/SS
PIC16F1782T-E/SS
PIC16F1782T-I/SS
PIC16F1783-E/SS
PIC16F1783-I/SS
PIC16F1783T-I/SS
PIC16F1786-E/SS
PIC16F1786-I/SS
PIC16F1786T-I/SS
PIC16F1788-E/SS



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<b>CATALOG_PART_NBR</b>
PIC16F1788-I/SS
PIC16F1788-I/SSC01
PIC16F1788T-E/SS
PIC16F1788T-I/SS
PIC16F1788T-I/SS023
PIC16F1788T-I/SSC01
PIC16F1933-E/SS
PIC16F1933-I/SS
PIC16F1933-I/SSC01
PIC16F1933T-E/SS
PIC16F1933T-I/SS
PIC16F1936-E/SS
PIC16F1936-I/SS
PIC16F1936-I/SS029
PIC16F1936-I/SSC01
PIC16F1936-I/SSC03
PIC16F1936T-E/SS
PIC16F1936T-I/SS
PIC16F1936T-I/SSC03
PIC16F1938-E/SS
PIC16F1938-I/SS
PIC16F1938-I/SSC03
PIC16F1938T-E/SS
PIC16F1938T-I/SS
PIC16F1938T-I/SSC03
PIC16F722A-E/SS
PIC16F722A-I/SS
PIC16F722A-I/SS023
PIC16F722AT-E/SS
PIC16F722AT-I/SS
PIC16F722AT-I/SS020
PIC16F722AT-I/SS021
PIC16F722AT-I/SS022
PIC16F722AT-I/SS024
PIC16F722-E/SS
PIC16F722-I/SS
PIC16F722T-E/SS
PIC16F722T-I/SS
PIC16F723A-E/SS
PIC16F723A-I/SS
PIC16F723AT-E/SS
PIC16F723AT-I/SS
PIC16F723-E/SS

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC16F723-I/SS
PIC16F723T-E/SS
PIC16F723T-I/SS
PIC16F726-E/SS
PIC16F726-I/SS
PIC16F726-I/SS035
PIC16F726-I/SS040
PIC16F726-I/SSC06
PIC16F726T-E/SS
PIC16F726T-I/SS
PIC16F726T-I/SS021
PIC16F726T-I/SS022
PIC16F726T-I/SS024
PIC16F726T-I/SS025
PIC16F726T-I/SS026
PIC16F726T-I/SS027
PIC16F726T-I/SS028
PIC16F726T-I/SS029
PIC16F726T-I/SS030
PIC16F726T-I/SS031
PIC16F726T-I/SS032
PIC16F726T-I/SS034
PIC16F726T-I/SS036
PIC16F726T-I/SS037
PIC16F726T-I/SS038
PIC16F726T-I/SS039
PIC16F726T-I/SSC06
PIC16LF1512-E/SS
PIC16LF1512-I/SS
PIC16LF1512T-I/SS
PIC16LF1513-E/SS
PIC16LF1513-I/SS
PIC16LF1513T-I/SS
PIC16LF1516-E/SS
PIC16LF1516-I/SS
PIC16LF1516-I/SSC04
PIC16LF1516T-I/SS
PIC16LF1516T-I/SSC04
PIC16LF1518-E/SS
PIC16LF1518-I/SS
PIC16LF1518T-I/SS
PIC16LF1566-E/SS
PIC16LF1566-I/SS

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC16LF1566T-I/SS
PIC16LF1713-E/SS
PIC16LF1713-I/SS
PIC16LF1713T-I/SS
PIC16LF1716-E/SS
PIC16LF1716-I/SS
PIC16LF1716T-I/SS
PIC16LF1718-E/SS
PIC16LF1718-I/SS
PIC16LF1718T-I/SS
PIC16LF1773-E/SS
PIC16LF1773-I/SS
PIC16LF1773T-I/SS
PIC16LF1776-E/SS
PIC16LF1776-I/SS
PIC16LF1776T-I/SS
PIC16LF1778-E/SS
PIC16LF1778-I/SS
PIC16LF1778T-I/SS
PIC16LF1782-E/SS
PIC16LF1782-I/SS
PIC16LF1782T-I/SS
PIC16LF1783-E/SS
PIC16LF1783-I/SS
PIC16LF1783-I/SSC01
PIC16LF1783-I/SSC02
PIC16LF1783T-I/SS
PIC16LF1783T-I/SSC01
PIC16LF1783T-I/SSC02
PIC16LF1786-E/SS
PIC16LF1786-I/SS
PIC16LF1786T-I/SS
PIC16LF1788-E/SS
PIC16LF1788-I/SS
PIC16LF1788T-I/SS
PIC16LF1902-E/SS
PIC16LF1902-I/SS
PIC16LF1902T-I/SS
PIC16LF1903-E/SS
PIC16LF1903-I/SS
PIC16LF1903T-I/SS
PIC16LF1906-E/SS
PIC16LF1906-I/SS

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC16LF1906T-I/SS
PIC16LF1933-E/SS
PIC16LF1933-I/SS
PIC16LF1933T-E/SS
PIC16LF1933T-I/SS
PIC16LF1936-E/SS
PIC16LF1936-I/SS
PIC16LF1936T-I/SS
PIC16LF1938-E/SS
PIC16LF1938-I/SS
PIC16LF1938T-I/SS
PIC16LF1938T-I/SS020
PIC16LF1938T-I/SS022
PIC16LF1938T-I/SS024
PIC16LF722A-E/SS
PIC16LF722A-I/SS
PIC16LF722AT-I/SS
PIC16LF722-E/SS
PIC16LF722-I/SS
PIC16LF722T-I/SS
PIC16LF723A-E/SS
PIC16LF723A-I/SS
PIC16LF723A-I/SS021
PIC16LF723A-I/SSC01
PIC16LF723A-I/SSC02
PIC16LF723AT-I/SS
PIC16LF723AT-I/SS020
PIC16LF723AT-I/SS021
PIC16LF723AT-I/SS023
PIC16LF723AT-I/SS024
PIC16LF723AT-I/SS025
PIC16LF723AT-I/SS026
PIC16LF723AT-I/SS027
PIC16LF723AT-I/SSC02
PIC16LF723-E/SS
PIC16LF723-I/SS
PIC16LF723T-I/SS
PIC16LF726-E/SS
PIC16LF726-I/SS
PIC16LF726-I/SSC02
PIC16LF726T-I/SS
PIC16LF726T-I/SS020
PIC16LF726T-I/SS021

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC16LF726T-I/SS022
PIC16LF726T-I/SS023
PIC18F23K20-E/SS
PIC18F23K20-I/SS
PIC18F23K20T-E/SS
PIC18F23K20T-E/SSC04
PIC18F23K20T-I/SS
PIC18F23K22-E/SS
PIC18F23K22-I/SS
PIC18F23K22T-E/SS
PIC18F23K22T-I/SS
PIC18F24K20-E/SS
PIC18F24K20-I/SS
PIC18F24K20-I/SSC03
PIC18F24K20T-E/SS
PIC18F24K20T-I/SS
PIC18F24K20T-I/SS031
PIC18F24K20T-I/SSC01
PIC18F24K20T-I/SSC03
PIC18F24K20T-I/SSC04
PIC18F24K20T-I/SSHP2
PIC18F24K22-E/SS
PIC18F24K22-I/SS
PIC18F24K22T-I/SS
PIC18F24K50-E/SS
PIC18F24K50-I/SS
PIC18F24K50T-I/SS
PIC18F25K20-E/SS
PIC18F25K20-E/SSC13
PIC18F25K20-E/SSC14
PIC18F25K20-I/SS
PIC18F25K20-I/SSC01
PIC18F25K20-I/SSC09
PIC18F25K20-I/SSC15
PIC18F25K20-I/SSLPR
PIC18F25K20T-E/SS
PIC18F25K20T-E/SSC04
PIC18F25K20T-E/SSC13
PIC18F25K20T-E/SSC14
PIC18F25K20T-I/SS
PIC18F25K20T-I/SS028
PIC18F25K20T-I/SSC01
PIC18F25K20T-I/SSC09

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<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC18F25K20T-I/SSC15
PIC18F25K20T-I/SSC17
PIC18F25K22-E/SS
PIC18F25K22-I/SS
PIC18F25K22T-E/SS
PIC18F25K22T-I/SS
PIC18F25K50-E/SS
PIC18F25K50-I/SS
PIC18F25K50T-I/SS
PIC18F25K80-E/SS
PIC18F25K80-H/SS
PIC18F25K80-I/SS
PIC18F25K80T-E/SS
PIC18F25K80T-I/SS
PIC18F26K20-E/SS
PIC18F26K20-E/SSC04
PIC18F26K20-E/SSC05
PIC18F26K20-I/SS
PIC18F26K20-I/SSLPR
PIC18F26K20T-E/SS
PIC18F26K20T-E/SSC04
PIC18F26K20T-E/SSC05
PIC18F26K20T-I/SS
PIC18F26K20T-I/SS027
PIC18F26K20T-I/SS031
PIC18F26K20T-I/SS038
PIC18F26K20T-I/SS039
PIC18F26K20T-I/SS041
PIC18F26K20T-I/SS044
PIC18F26K20T-I/SSLPR
PIC18F26K22-E/SS
PIC18F26K22-I/SS
PIC18F26K22T-E/SS
PIC18F26K22T-I/SS
PIC18F26K22T-I/SS023
PIC18F26K80-E/SS
PIC18F26K80-H/SS
PIC18F26K80-I/SS
PIC18F26K80T-E/SS
PIC18F26K80T-H/SS
PIC18F26K80T-I/SS
PIC18LF23K22-E/SS
PIC18LF23K22-I/SS

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<b>CATALOG_PART_NBR</b>
PIC18LF23K22T-I/SS
PIC18LF24K22-E/SS
PIC18LF24K22-I/SS
PIC18LF24K22T-I/SS
PIC18LF24K50-E/SS
PIC18LF24K50-I/SS
PIC18LF24K50T-I/SS
PIC18LF25K22-E/SS
PIC18LF25K22-I/SS
PIC18LF25K22-I/SSC02
PIC18LF25K22T-E/SS
PIC18LF25K22T-I/SS
PIC18LF25K22T-I/SSC02
PIC18LF25K50-E/SS
PIC18LF25K50-I/SS
PIC18LF25K50T-I/SS
PIC18LF25K80-I/SS
PIC18LF25K80T-I/SS
PIC18LF26K22-E/SS
PIC18LF26K22-I/SS
PIC18LF26K22-I/SSC03
PIC18LF26K22T-E/SS
PIC18LF26K22T-I/SS
PIC18LF26K22T-I/SS021
PIC18LF26K22T-I/SS022
PIC18LF26K22T-I/SSC03
PIC18LF26K80-I/SS
PIC18LF26K80T-I/SS
PIC24F08KA102-E/SS
PIC24F08KA102-I/SS
PIC24F08KA102T-E/SS
PIC24F08KL302-E/SS
PIC24F08KL302-I/SS
PIC24F08KL302T-I/SS
PIC24F08KL402-E/SS
PIC24F08KL402-I/SS
PIC24F08KL402T-I/SS
PIC24F08KM202-I/SS
PIC24F16KA102-E/SS
PIC24F16KA102-I/SS
PIC24F16KA102T-I/SS
PIC24F16KA302-E/SS
PIC24F16KA302-I/SS

JAON-30IVHP500 - CCB 3001 Initial Notice: Qualification of MMT as an additional assembly site using CuPdAu bond wire in selected products of the 200K wafer technology available in 28L SSOP package.

Affected Catalog Part Numbers (CPN)

<b>PCN_JAON-30IVHP500</b>
<b>CATALOG_PART_NBR</b>
PIC24F16KA302T-I/SS
PIC24F16KL402-E/SS
PIC24F16KL402-I/SS
PIC24F16KL402T-I/SS
PIC24F16KM102-I/SS
PIC24F16KM202-I/SS
PIC24F32KA302-E/SS
PIC24F32KA302-I/SS
PIC24F32KA302T-I/SS
PIC24FV08KM202-I/SS
PIC24FV16KA302-E/SS
PIC24FV16KA302-I/SS
PIC24FV16KA302T-E/SS
PIC24FV16KA302T-I/SS
PIC24FV16KM102-I/SS
PIC24FV16KM202-E/SS
PIC24FV16KM202-I/SS
PIC24FV16KM202T-E/SS
PIC24FV16KM202T-I/SS
PIC24FV32KA302-E/SS
PIC24FV32KA302-I/SS
PIC24FV32KA302T-E/SS
PIC24FV32KA302T-I/SS